High-speed non-contact
Ultrasonic Inline Inspection
Functionality

XARION’s laser-based technology enables the ultrasonic inspection of semiconductor components without any coupling liquid. A single laser pulse generates an acoustic fingerprint of each sample revealing internal delaminations and defects with a throughput of up to 1000 samples per second. The fully non-contact sensor technology can be easily integrated into a high-volume production line, saving costs for offline analysis, and ensuring inspection of 100% of the components, e.g. packaged devices for the automotive sector.

Features

• 100% documented safety for your customer
• Unique non-contact single-shot ultrasound technology
• Fully automated inline inspection of up to 1000 samples per second
• Easy integration into high-throughput production environment:
  • No water coupling, and no drying of samples necessary
  • No interference with other production steps
• Combination with offline non-contact imaging of defective components for further analysis possible

Contact:
opticalmicrophones@xarion.com
+43 1 9076076